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(12) **United States Design Patent**
Wang

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(54) **THERMAL INFRARED IMAGER**
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(**) Term: **14 Years**
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D16/132, 133, 206, 200, 201, 203; 359/630;
D10/46, 66, 50, 70; 33/290, 291, 292, 285
See application file for complete search history.

(56) **References Cited**
U.S. PATENT DOCUMENTS
D203,233 S * 12/1965 Olson D16/205
3,606,065 A * 9/1971 Carlson 220/4.02
D228,027 S * 7/1973 Heckel et al. D16/132
D240,333 S * 6/1976 Chesnut D16/132
D287,977 S * 1/1987 Cannon D16/132
D300,039 S * 2/1989 Huckenbeck D16/132
D322,084 S * 12/1991 Tabuchi D16/203
D325,041 S * 3/1992 Wissing et al. D16/132
D351,397 S * 10/1994 Dor D16/130
5,465,117 A * 11/1995 Ide et al. 348/373
D369,613 S * 5/1996 Palmer D16/132
D380,222 S * 6/1997 Bryant D16/132
5,986,803 A * 11/1999 Kelly 359/409
D418,853 S * 1/2000 Kubota D16/203
D424,081 S * 5/2000 Gordon D16/130
D484,900 S * 1/2004 Lee et al. D16/133
D496,672 S * 9/2004 Hines et al. D16/133
D533,573 S * 12/2006 Barber et al. D16/130
D539,317 S * 3/2007 Tonhofer D16/132
D544,897 S * 6/2007 Mullett et al. D16/133

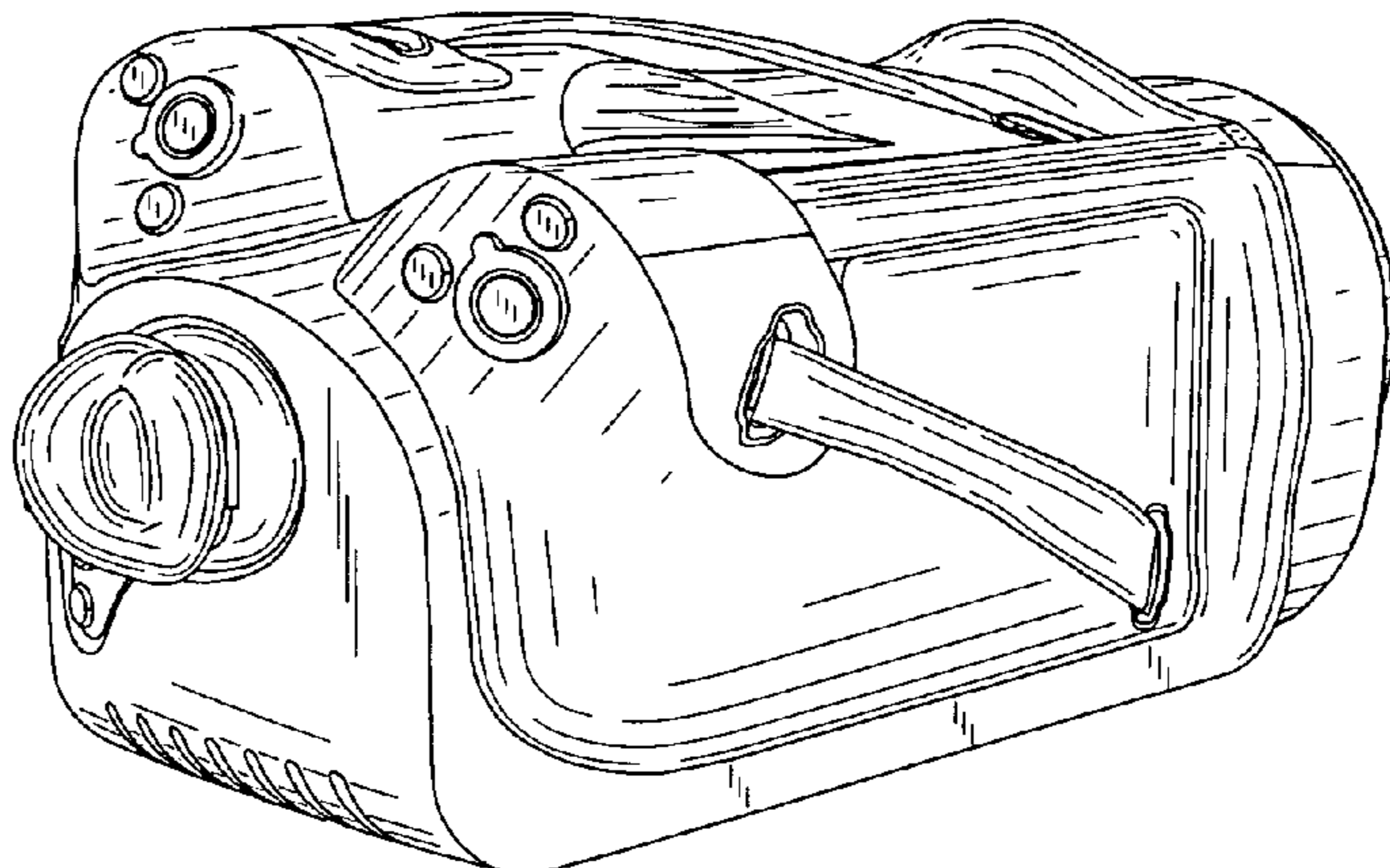
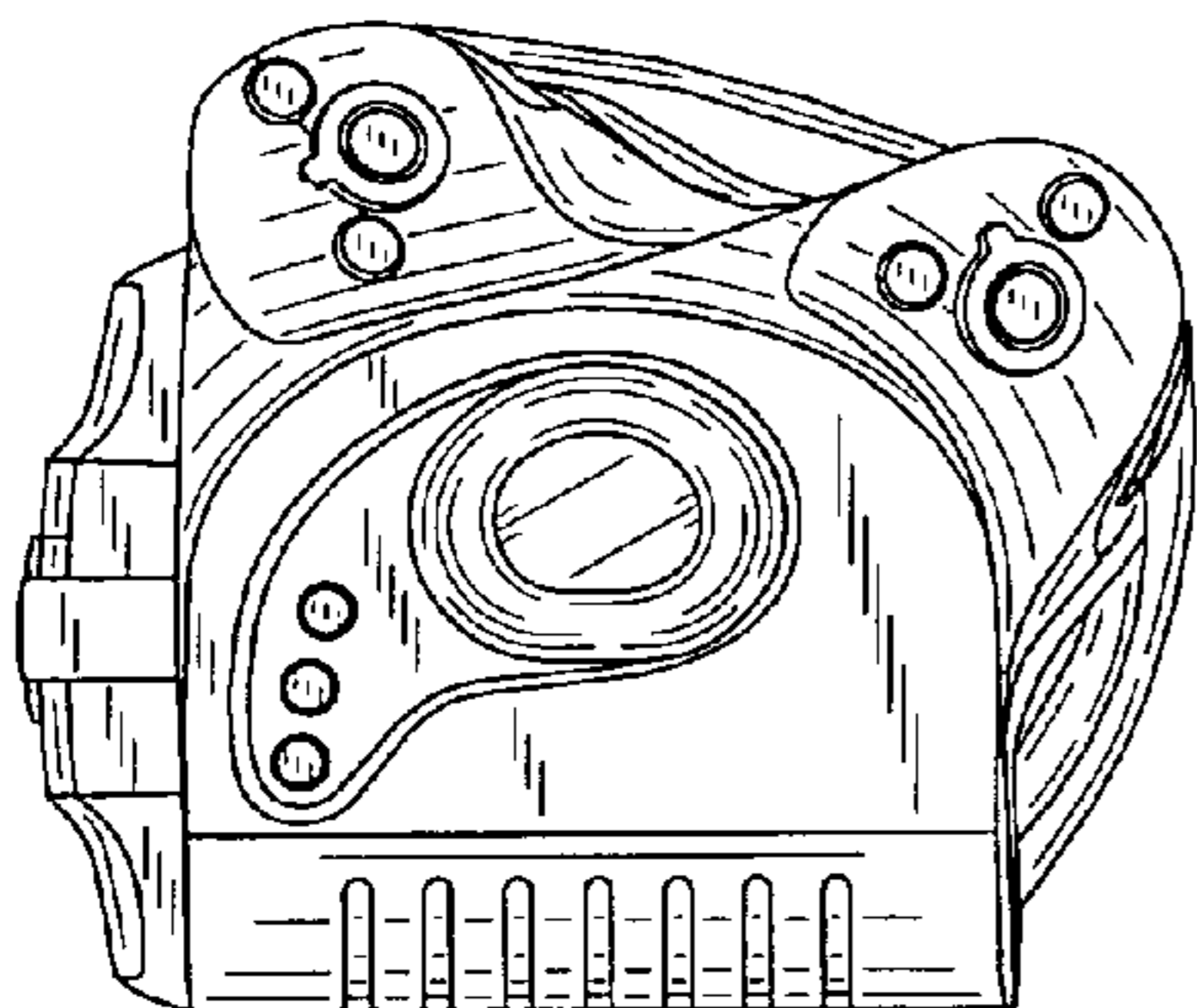
D547,780 S * 7/2007 Meinzer D16/132
D564,555 S * 3/2008 Palmer D16/132
D578,599 S * 10/2008 Cheng D22/109
D603,436 S * 11/2009 Hamilton D16/132
D606,572 S * 12/2009 Samson et al. D16/203

* cited by examiner
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Jiwen Chen

(57) **CLAIM**
I claim the ornamental design for the thermal infrared imager, as shown and described.

DESCRIPTION
FIG. 1 is a front elevational view of the thermal infrared imager when it is in a closed position;
FIG. 2 is a rear elevational view of the thermal infrared imager when it is in a closed position;
FIG. 3 is a bottom plan view of the thermal infrared imager when it is in a closed position;
FIG. 4 is a top plan view of the thermal infrared imager when it is in a closed position;
FIG. 5 is a left side view of the thermal infrared imager when it is in a closed position;
FIG. 6 is a right side view of the thermal infrared imager when it is in a closed position;
FIG. 7 is a rear perspective view of the thermal infrared imager when it is in a closed position;
FIG. 8 is a right side view of the thermal infrared imager when it is in an open position;
FIG. 9 is a front elevational view of the thermal infrared imager when it is in an open position;
FIG. 10 is a rear elevational view of the thermal infrared imager when it is in an open position;
FIG. 11 is a top plan view of the thermal infrared imager when it is in an open position; and,
FIG. 12 is a bottom plan view of the thermal infrared imager when it is in an open position.
The broken lines form no part of the claimed design.

1 Claim, 6 Drawing Sheets



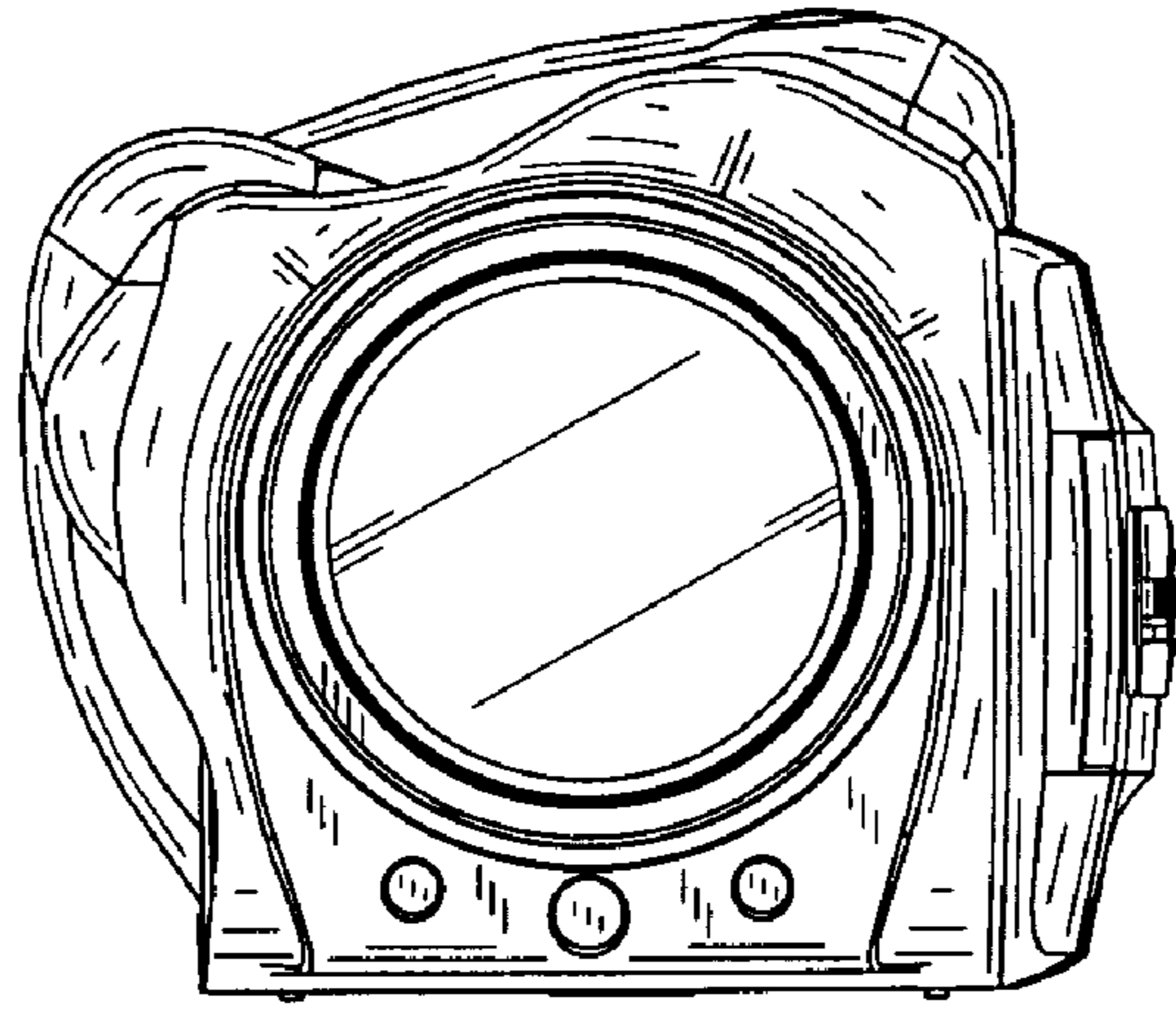


Fig. 1

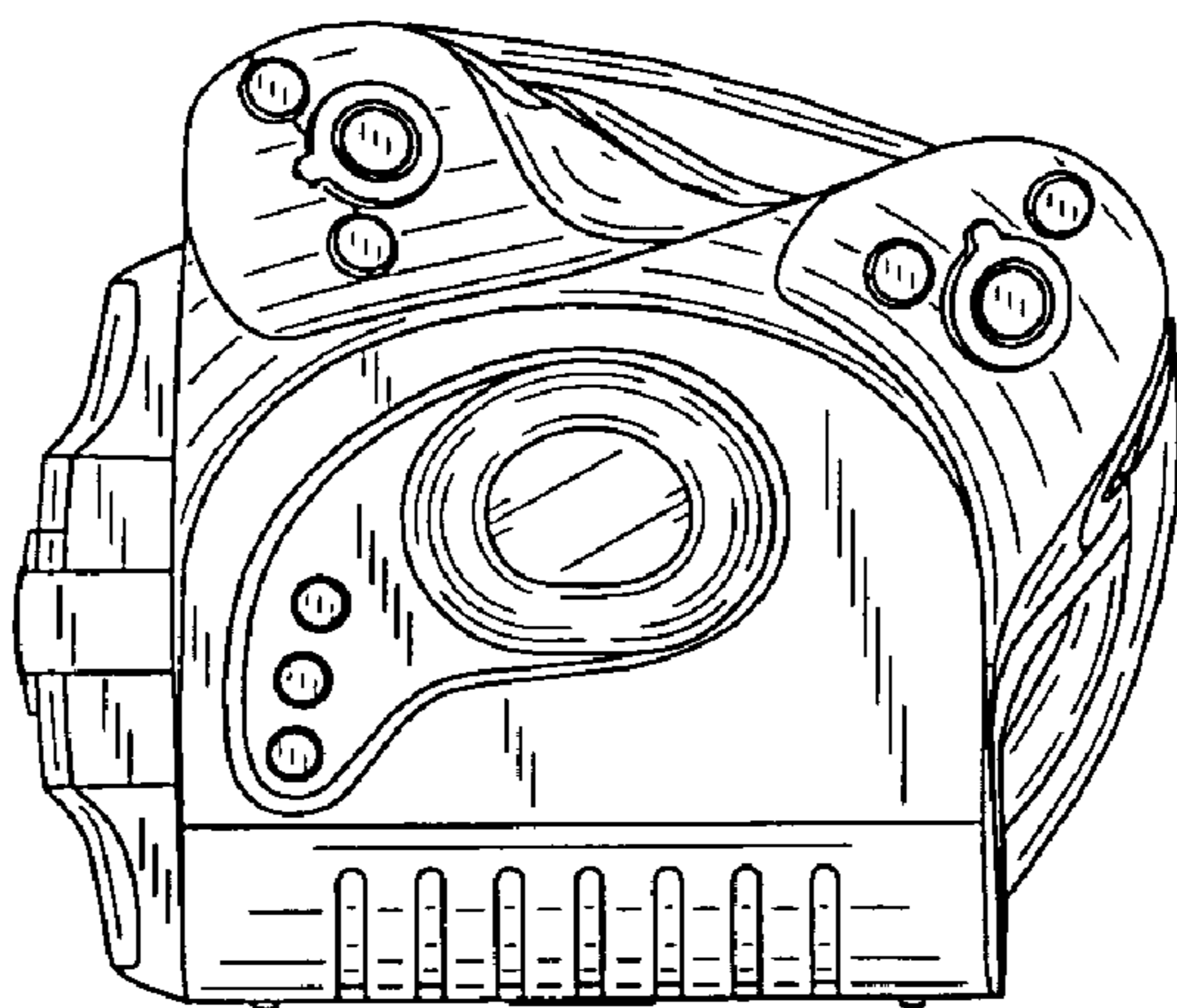


Fig. 2

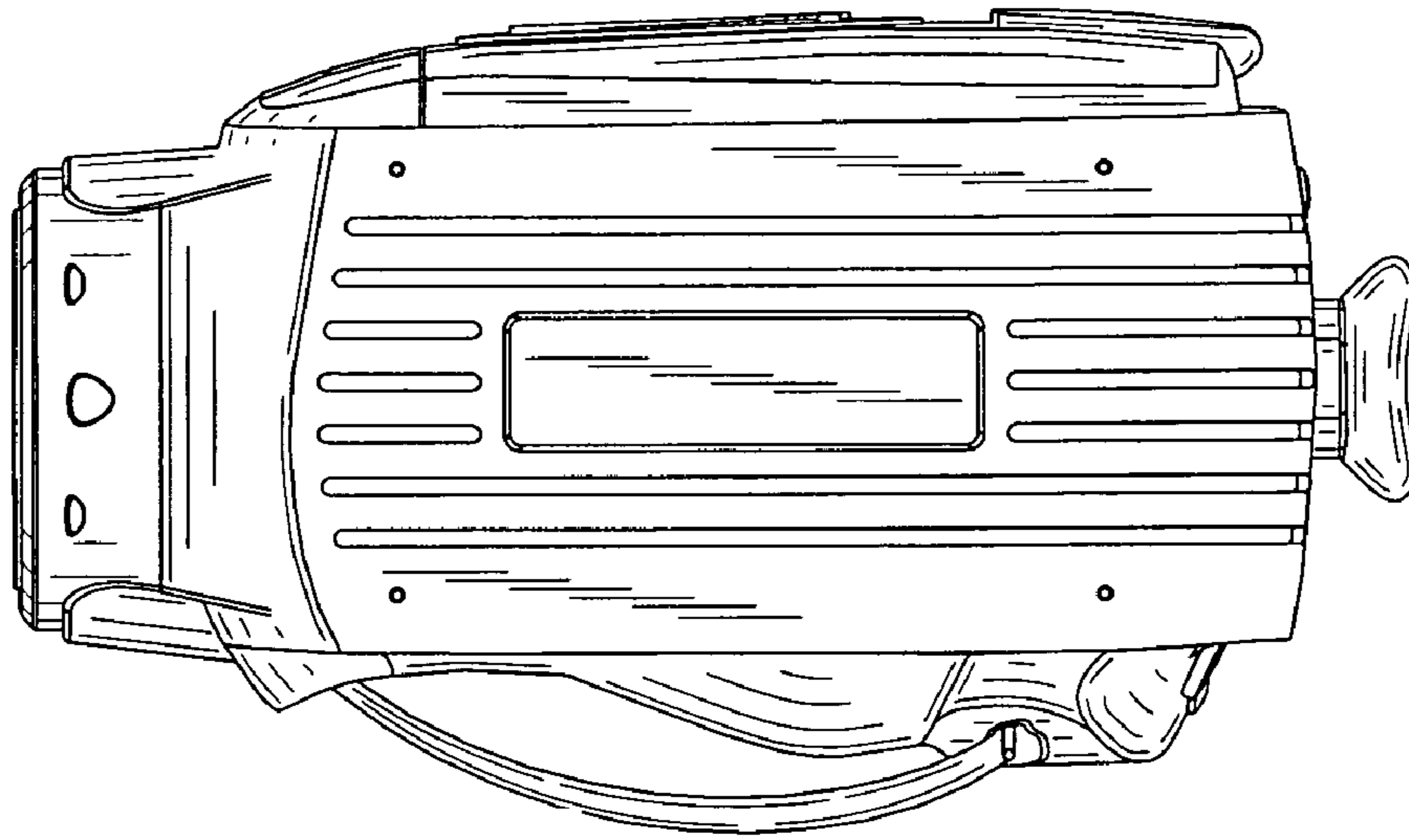


Fig. 3

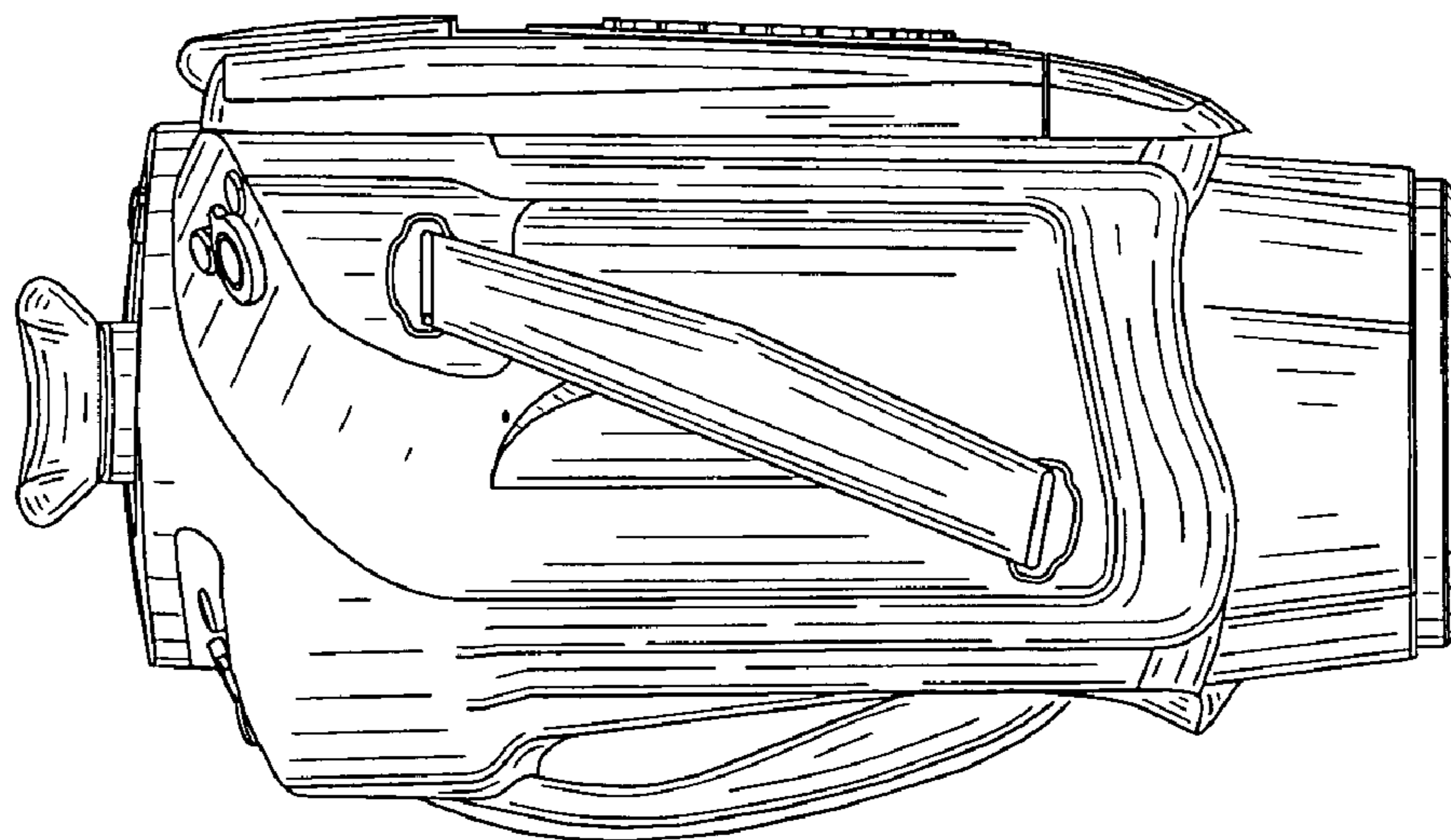


Fig. 4

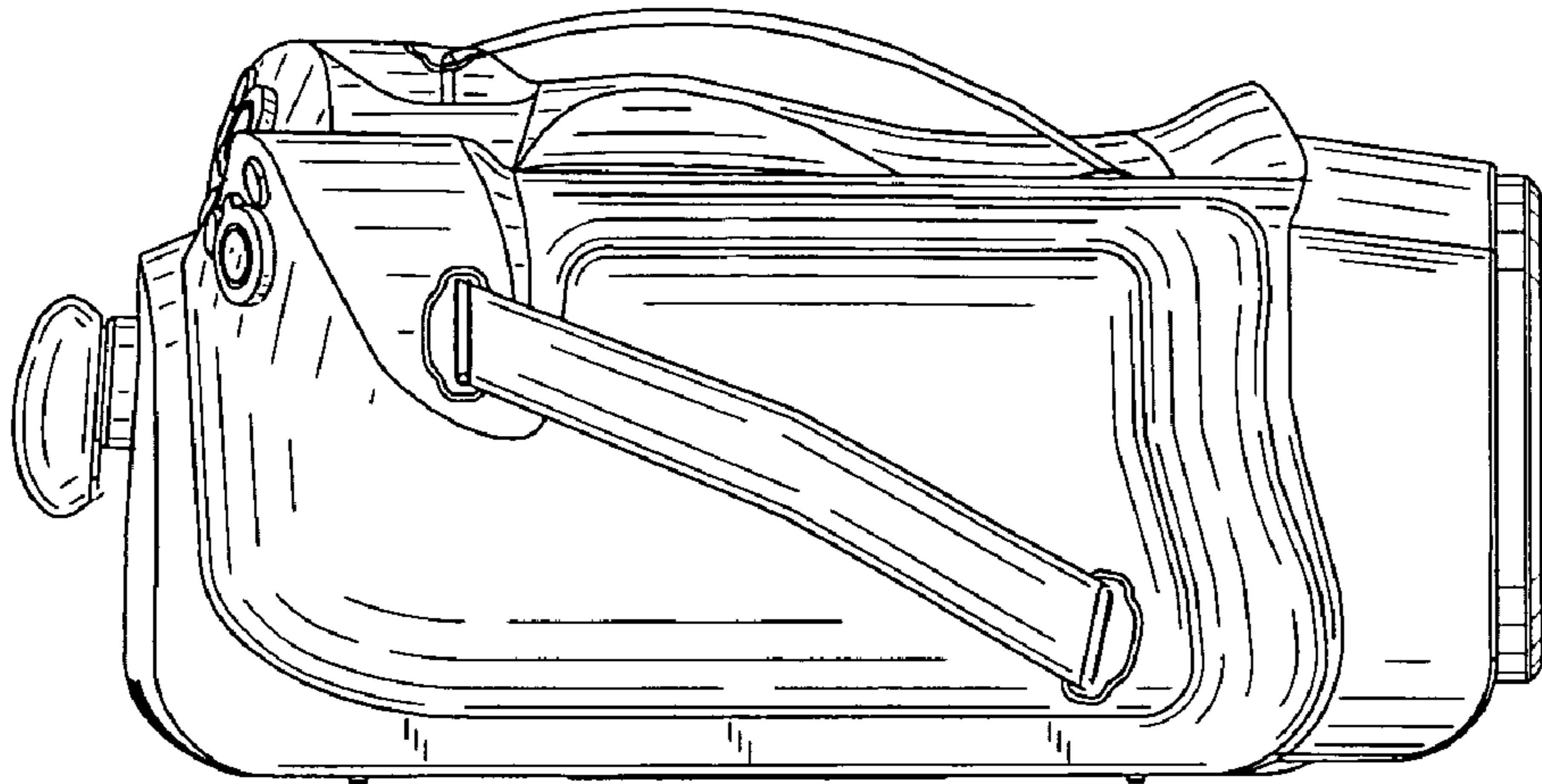


Fig. 5

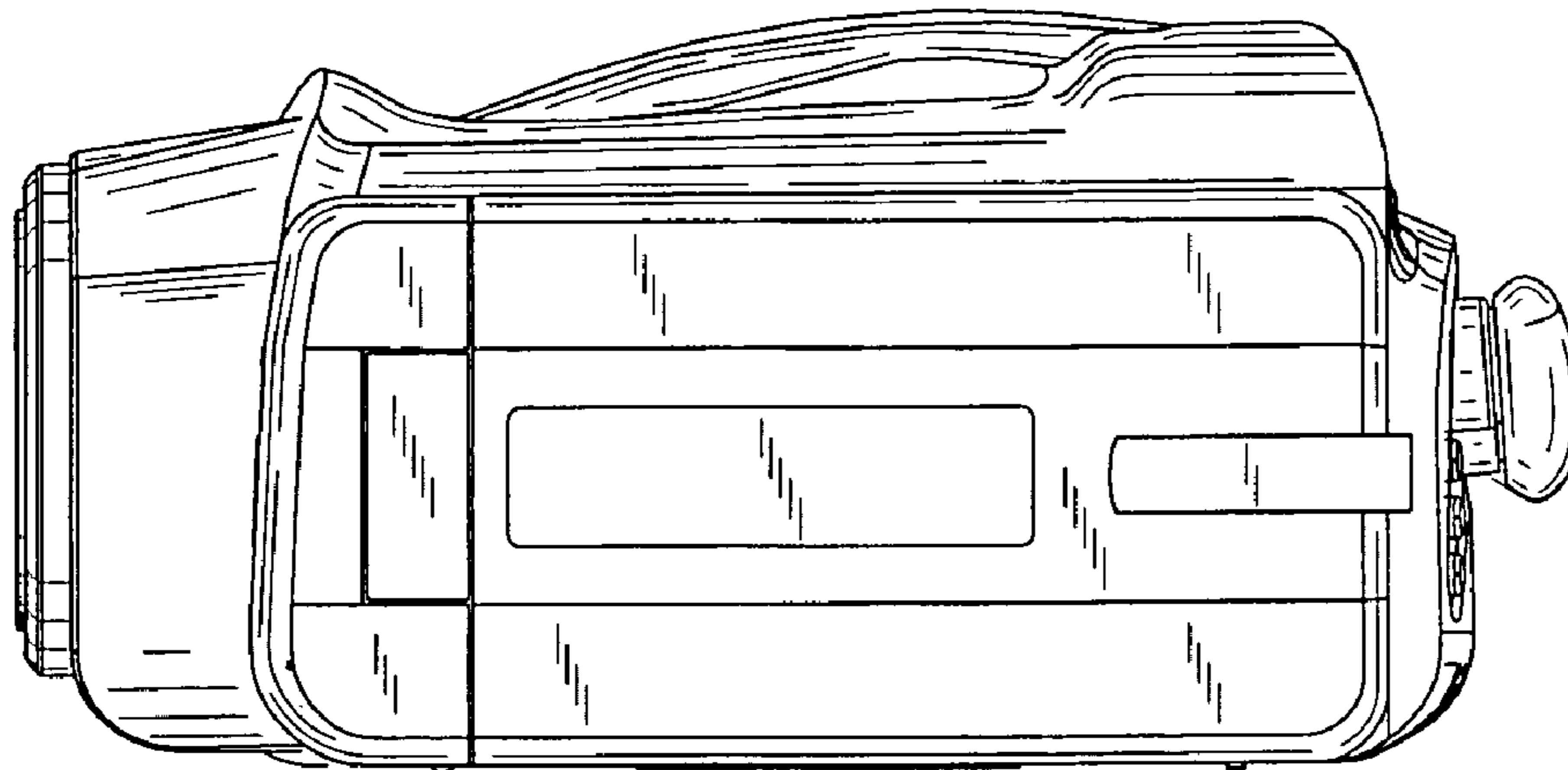


Fig. 6

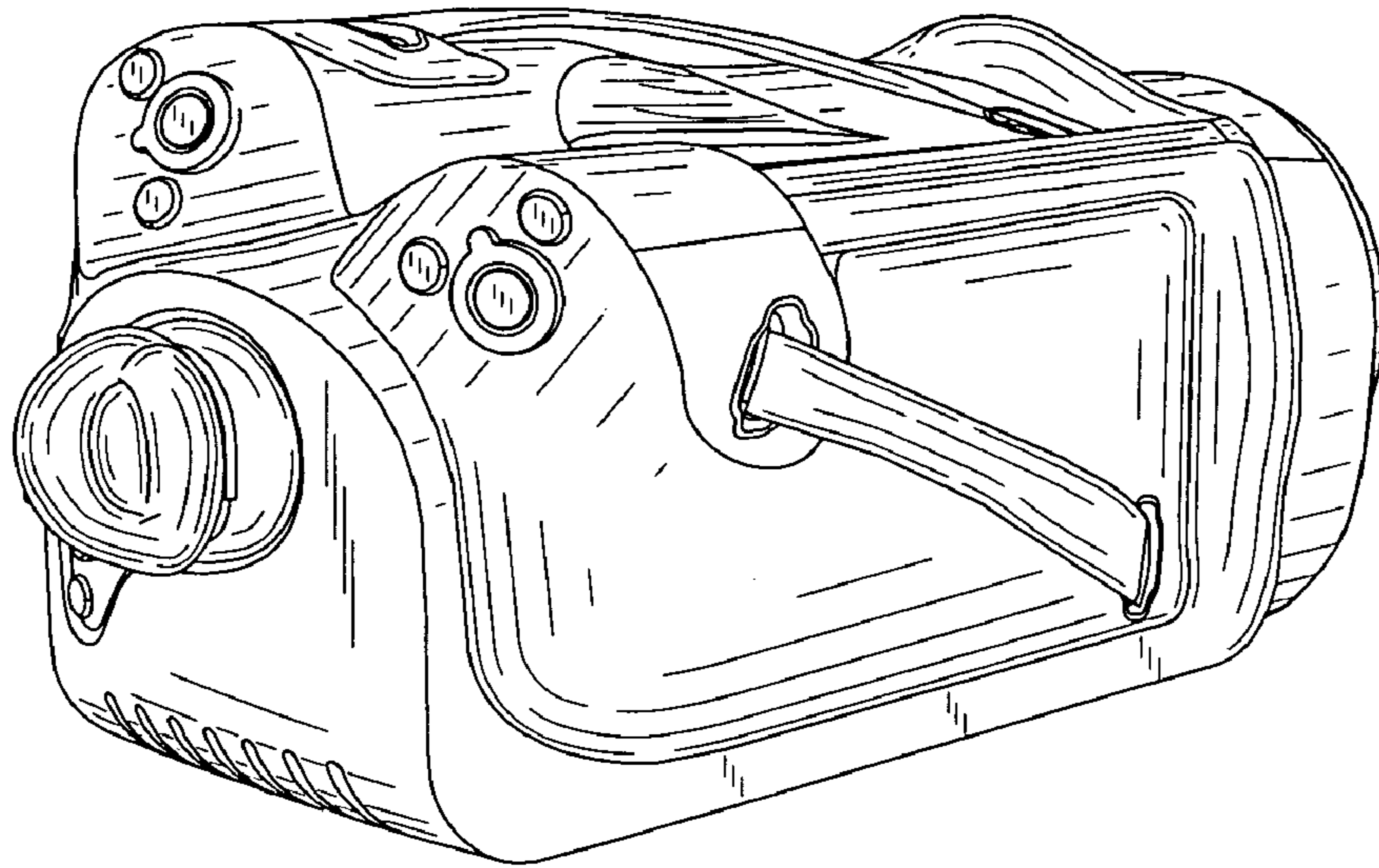


Fig. 7

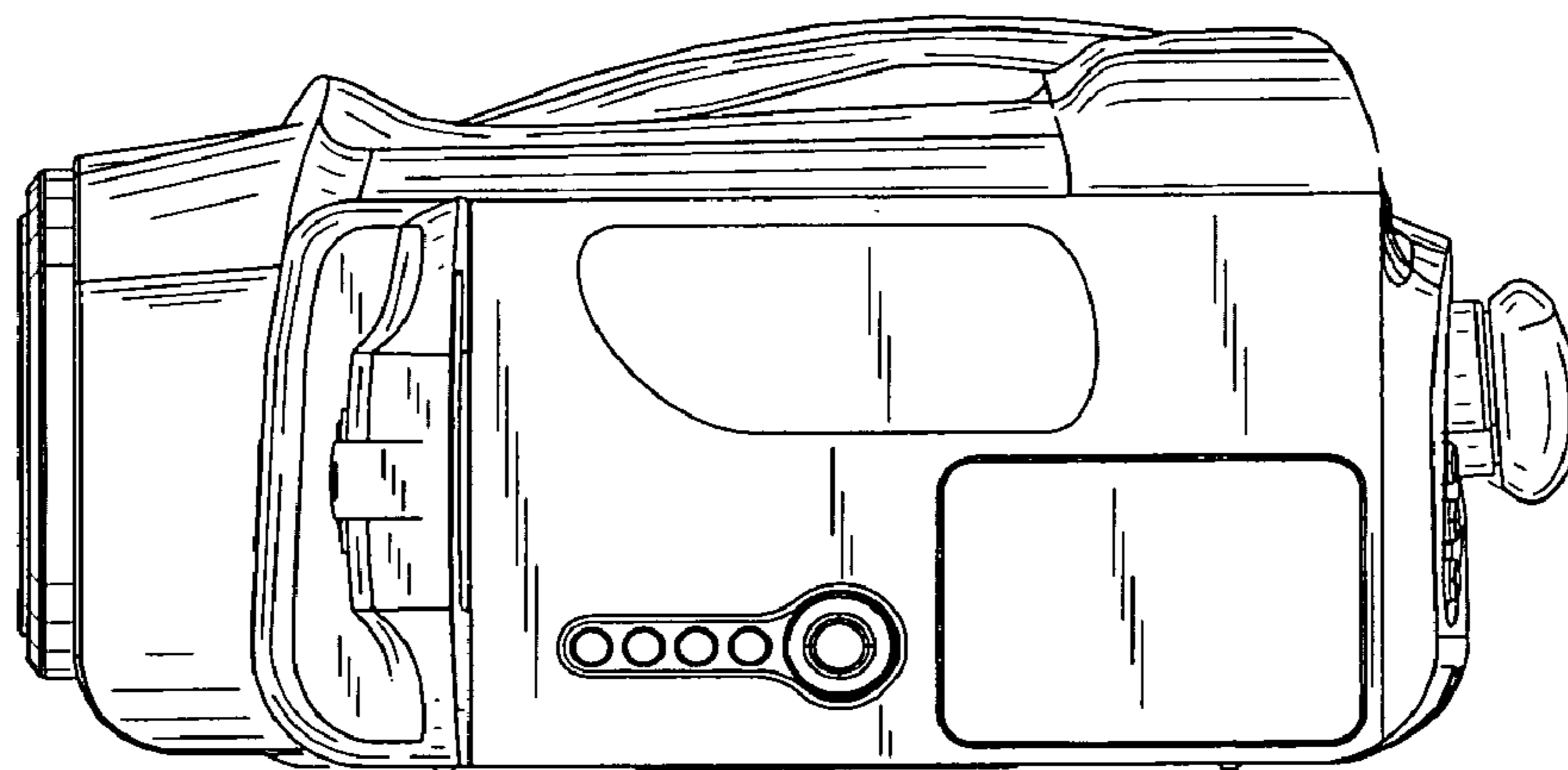


Fig. 8

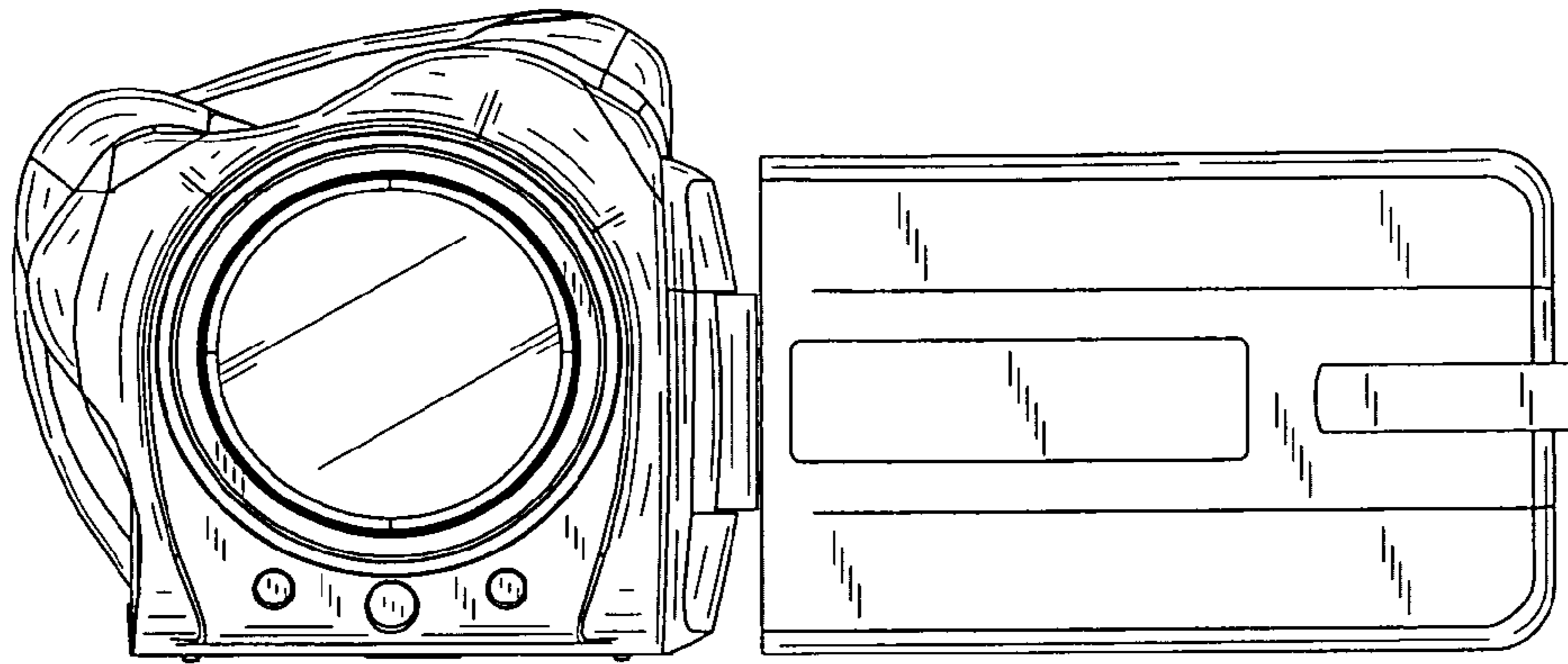


Fig. 9

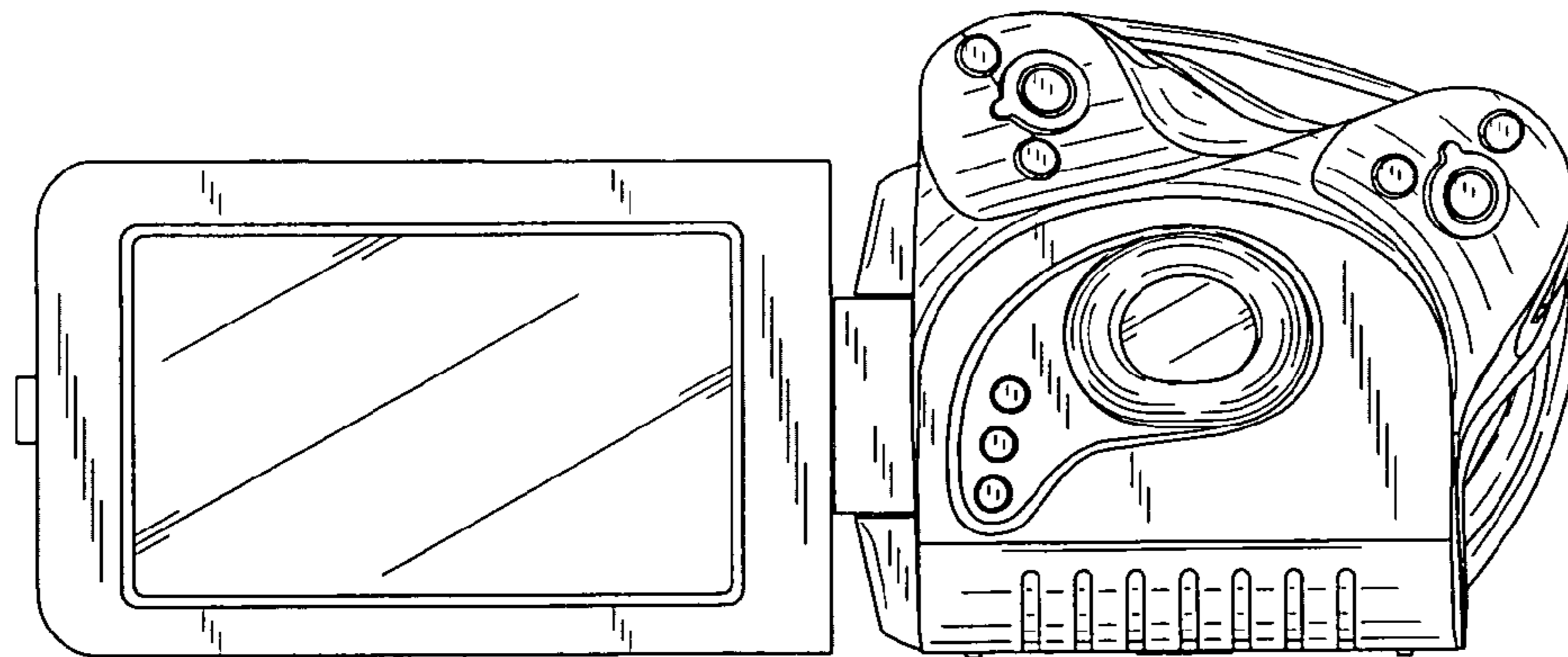


Fig. 10

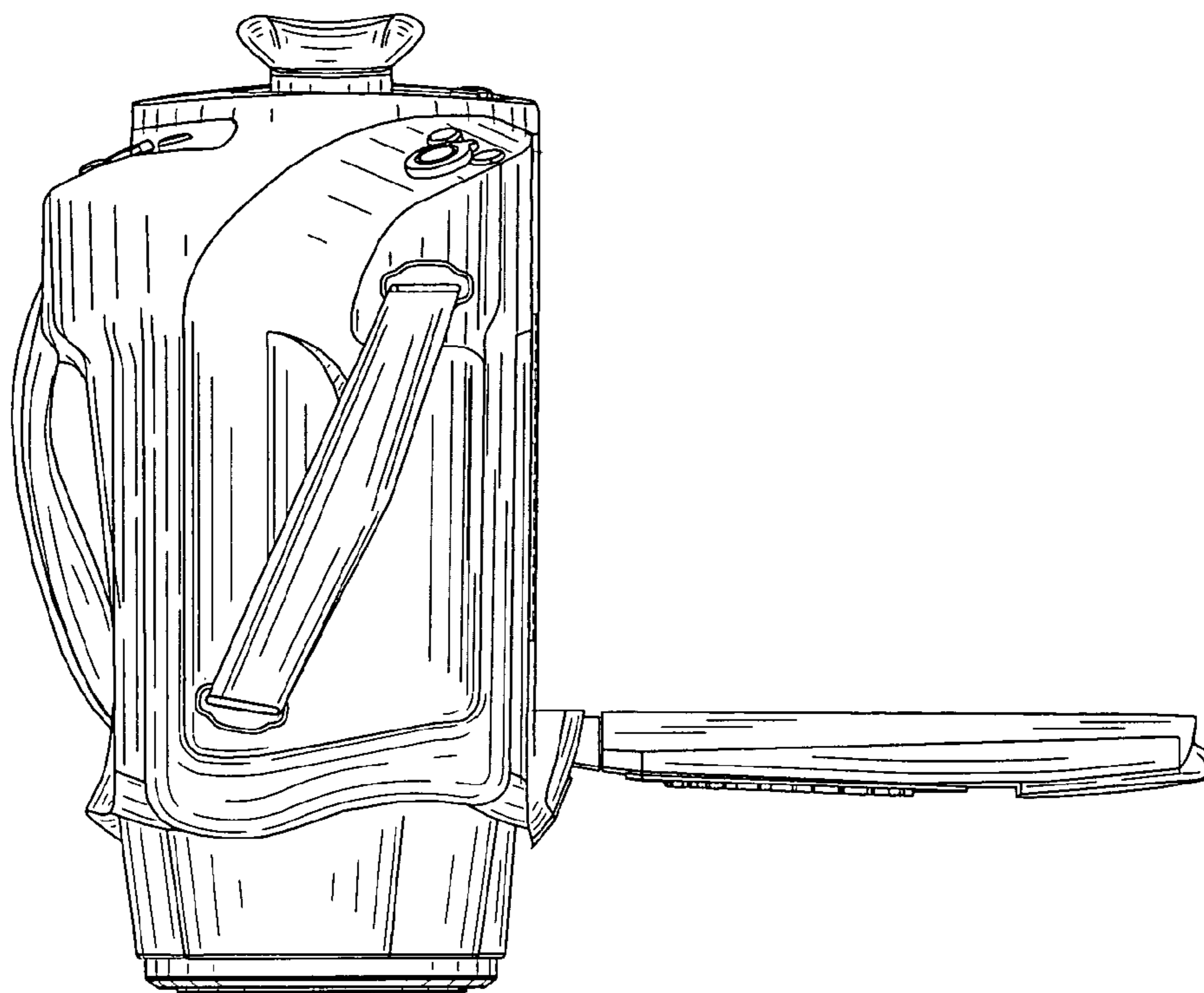


Fig. 11

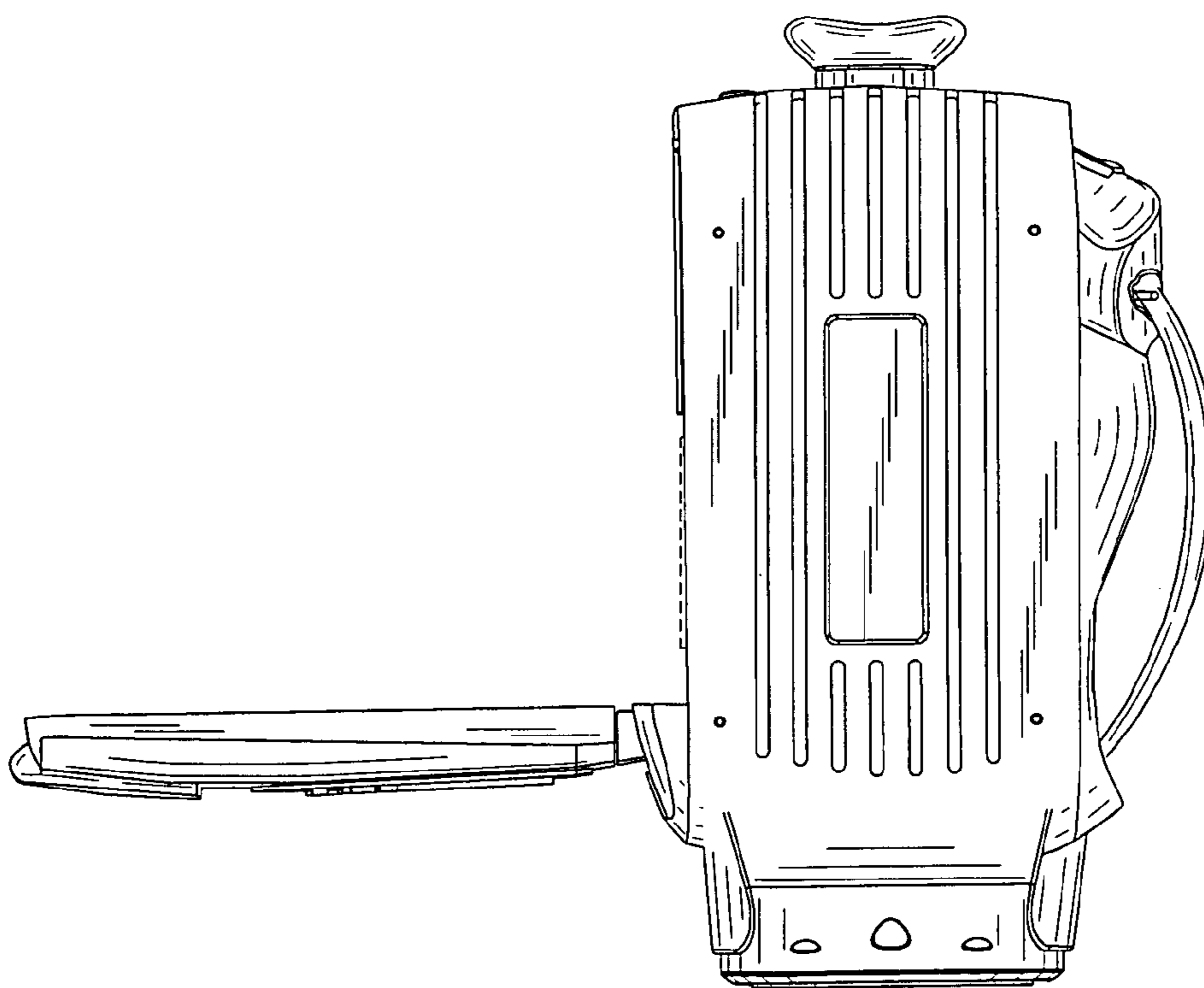


Fig. 12